

Hyve Orion™ Featuring NVIDIA HGX™ Rubin NVL8 Direct Liquid Cooled (DLC)

Built for AI and high-performance computing for every data center



Key Features

- > NVIDIA Rubin with Integrated NVIDIA ConnectX®-9 Networking
- > Dual Intel Xeon 6700 Series Processors with P-Cores (350W) TDP
- > Direct Liquid Cooled Optimized
- > Front IO Serviceable

Specifications

Dimensions	19" 2RU (Height: 87MM Width: 449.6MM Depth: 802.35MM)	Storage	Up to 8 x Hot-Swap E1.S NVMe Drives
Headnode	Intel	GPU	NVIDIA SXM8: HGX™ Rubin NVL8
CPU	Intel Xeon 6700 Series Processors	Thermal Solution	Direct Liquid Cooled (DLC)
BIOS	AMI 64MB SPI	System Management	DC-SCM AST2600 + eRoT (CEC1736)
Socket	LGA-4710		
Memory	32 x DIMMs 6400/5200MT/s (1DPC/2DPC)		
LAN	1 x 1GB RJ45		



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